

## 3.3V CMOS Static RAM 1 Meg (128K x 8-Bit) Revolutionary Pinout

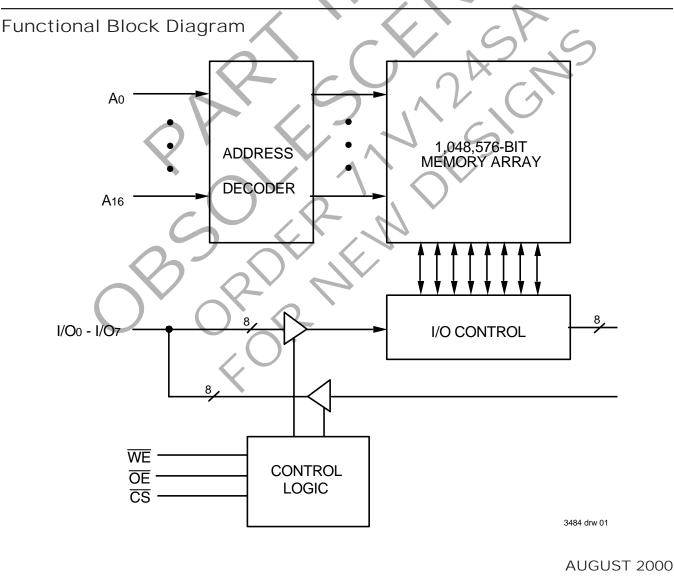
#### Features

- 128K x 8 advanced high-speed CMOS static RAM
- JEDEC revolutionary pinout (center power/GND) for reduced noise
- Commercial (0°C to +70°C) and Industrial (-40°C to +85°C) temperature options
- Equal access and cycle times — Industrial and Commercial: 15/20ns
- One Chip Select plus one Output Enable pin
- Bidirectional inputs and outputs directly
- LVTTL-compatible
- Low power consumption via chip deselect
- Available in 32-pin 400 mil Plastic SOJ.

### Description

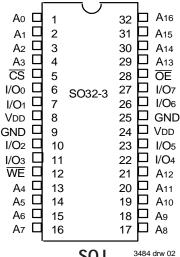
The IDT71V124 is a 1,048,576-bit high-speed static RAM organized as 128K x 8. It is fabricated using IDT's high-performance, highreliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a costeffective solution for high-speed memory needs. The JEDEC center power/GND pinout reduces noise generation and improves system performance.

The IDT71V124 has an output enable pin which operates as fast as 7ns, with address access times as fast as 15ns available. All bidirectional inputs and outputs of the IDT71V124 are LVTTL-compatible and operation is from a single 3.3V supply. Fully static asynchronous circuitry is used; no clocks or refreshes are required for operation. The IDT71V124 is packaged in 32-pin 400 mil Plastic SOJ.



#### IDT71V124, 3.3V CMOS Static RAM 1 Meg (128K x 8-Bit), Revolutionary Pinout

### Pin Configuration



SOJ **Top View** 

#### Truth Table<sup>(1,2)</sup>

CS	ŌĒ	WE	I/O	Function
L	L	Н	DATAOUT	Read Data
L	Х	L	DATAIN	Write Data
L	Н	Н	High-Z	Output Disabled
Н	Х	Х	High-Z	Deselected – Standby (IsB)
VHC <sup>(3)</sup>	Х	Х	High-Z	Deselected – Standby (Isb1)
NOTEO				3484 tbl 01

#### NOTES:

1.  $H = V_{IH}$ ,  $L = V_{IL}$ , x = Don't care.

2.  $V_{LC} = 0.2V$ ,  $V_{HC} = V_{DD} - 0.2V$ .

3. Other inputs  $\geq$ VHC or  $\leq$ VLC.

#### Capacitance $(T_A = +25^{\circ}C, f = 1.0MHz, SOJ pa$

(17 - 123	$C_1 I = 1.00012, 303 pace$	(agc)		
Symbol	Parameter <sup>(1)</sup>	Conditions	Max.	Unit
Cin	Input Capacitance	Vin = 3dV	8	pF
Cı⁄o	I/O Capacitance	Vout = 3dV	8	pF
				3484 tbl 03

#### NOTE:

1. This parameter is guaranteed by device characterization, but is not production tested.

# DC Electrical Characteristics

(VDD = 3.3V ± 10%, Commercial and Industrial Temperature Ranges)

			IDT7	IV124	
Symbol	Parameter	Test Condition	Min.	Max.	Unit
lu	Input Leakage Current	$V_{DD} = Max., V_{IN} = GND to V_{DD}$		5	μA
ILO	Output Leakage Current	$V_{DD} = Max., \overline{CS} = V_{IH}, V_{OUT} = GND to V_{DD}$		5	μA
Vol	Output Low Voltage	IOL = 8mA, VDD = Min.		0.4	V
Vон	Output High Voltage	Ioh = $-8mA$ , Vdd = Min.	2.4		V

## 2

# Absolute Maximum Ratings<sup>(1)</sup>

Symbol	Rating	Value	Unit
Vterm <sup>(2)</sup>	Terminal Voltage with Respect to GND	$-0.5$ to $+4.1^{(2)}$	V
Та	Operating Temperature	0 to +70	٥C
Tbias	Temperature Under Bias	-55 to +125	٥C
Tstg	Storage Temperature	-55 to +125	٥C
Рт	Power Dissipation	0.5	W
Ιουτ	DC Output Current	50	mA
			3484 tbl 02

NOTES:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

2. VTERM must not exceed VDD + 0.5V.

# Recommended Operating Temperature and Supply Voltage

Grade	Temperature	GND	Vdd
Commercial	0°C to +70°C	0V	See Below
Industrial	-40°C to +85°C	0V	See Below
			3484 tbl 02a

## Recommended DC Operating Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vdd	Supply Voltage	3.0	3.3	3.6	۷
GND	Ground	0	0	0	۷
Vih	Input High Voltage	2.0		VDD +0.3	۷
VIL	Input Low Voltage	-0.3 <sup>(1)</sup>		0.8	۷
				3	484 tbl 04

NOTE:

1. VIL (min.) = -1V for pulse width less than 5ns, once per cycle.

#### **Commercial and Industrial Temperature Ranges**

3484 tbl 06

### DC Electrical Characteristics<sup>(1)</sup> (VDD = $3.3V \pm 10\%$ , VLC = 0.2V, VHC = VDD - 0.2V)

		71V12	24S15	71V12	24S20	
Symbol	Parameter	Com'l.	Ind.	Com'l.	Ind.	Unit
Icc	Dynamic Operating Current $\overline{CS} \leq V_{IL}$ , Outputs Open, VDD = Max., f = fMAX <sup>(2)</sup>	100	120	95	115	mA
Isb	Standby Power Supply Current (TTL Level) $\overline{\text{CS}} \ge \text{Vih}$ , Outputs Open, VDD = Max., f = fmax <sup>(2)</sup>	35	40	30	35	mA
ISB1	Full Standby Power Supply Current (CMOS Level) $\overline{CS} \ge VHc$ , Outputs Open, VDD = Max., f = 0 <sup>(2)</sup> $VIN \le VLc$ or VIN $\ge VHc$	5	7	5	7	mA

NOTES:

1. All values are maximum guaranteed values.

2. fmax = 1/trc (all address inputs are cycling at fmax); f = 0 means no address input lines are changing.

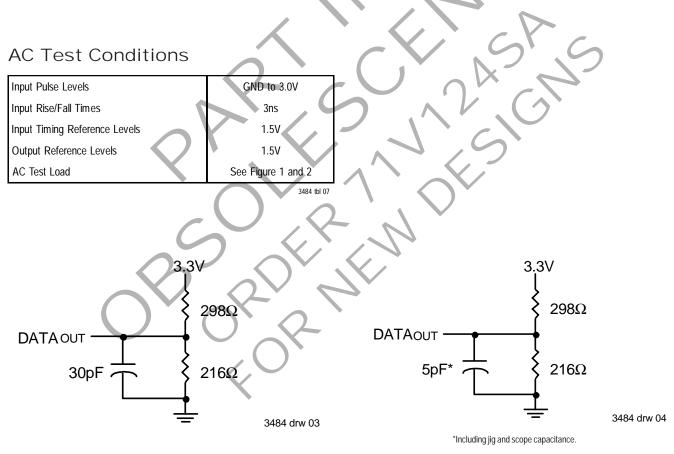


Figure 1. AC Test Load

Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz) IDT71V124, 3.3V CMOS Static RAM 1 Meg (128K x 8-Bit), Revolutionary Pinout

## AC Electrical Characteristics (VDD = 3.3V ± 10%, Commercial and Industrial Ranges)

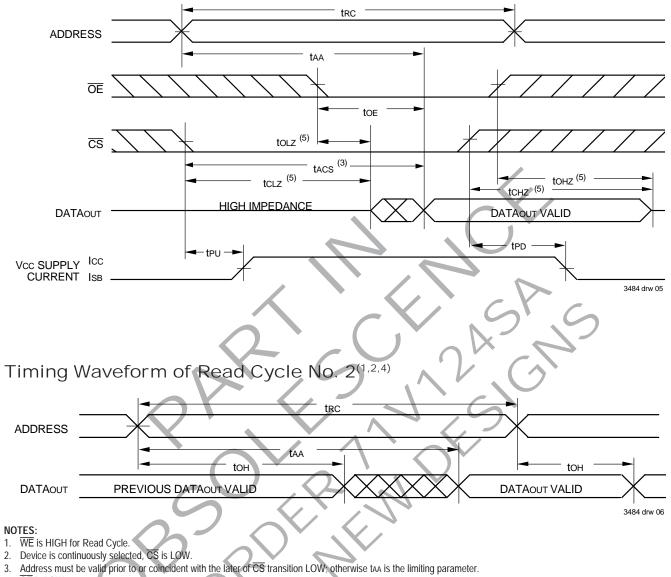
		71V1	24S15	71V1	24S20	
Symbol	Parameter	Min.	Max.	Min.	Max.	Unit
READ CYCLE				-	-	
trc	Read Cycle Time	15		20		ns
taa	Address Access Time		15		20	ns
tacs	Chip Select Access Time		15		20	ns
tclz <sup>(1)</sup>	Chip Select to Output in Low-Z	3		3		ns
tснz <sup>(1)</sup>	Chip Deselect to Output in High-Z	0	- 7	0	8	ns
toe	Output Enable to Output Valid		7		8	ns
tolz <sup>(1)</sup>	Output Enable to Output in Low-Z	0		0		ns
tонz <sup>(1)</sup>	Output Disable to Output in High-Z	0	5	0	7	ns
toн	Output Hold from Address Change	4	5	4	<b>n</b> -	ns
tpu <sup>(1)</sup>	Chip Select to Power-Up Time	0	K -	0	_	ns
tpd <sup>(1)</sup>	Chip Deselect to Power-Down Time	· F	15	<u>}</u>	20	ns
WRITE CYCL	E		·			
twc	Write Cycle Time	15	D-	20		ns
taw	Address Valid to End of Write	12		15		ns
tcw	Chip Select to End of Write	12		15		ns
tas	Address Set-up Time	0		0		ns
twp	Write Pulse Width	12		15		ns
twr	Write Recovery Time	0		0		ns
tow	Data Valid to End of Write	8		9		ns
tDH	Data Hold Time	0	—	0	_	ns
tow <sup>(1)</sup>	Output Active from End of Write	3		4	—	ns
twhz <sup>(1)</sup>	Write Enable to Output in High-Z	0	5	0	8	ns

NOTE:

1. This parameter guaranteed with the AC load (Figure 2) by device characterization, but is not production tested.

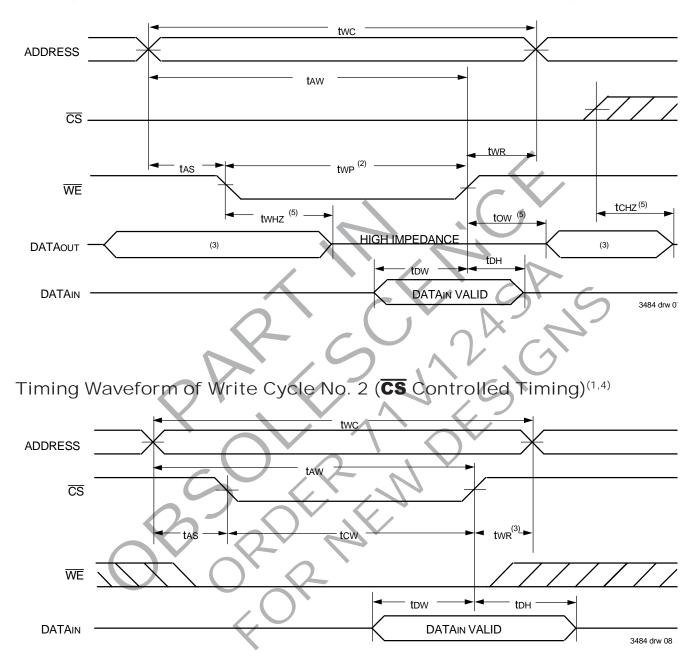
3484 tbl 08

## Timing Waveform of Read Cycle No. 1<sup>(1)</sup>



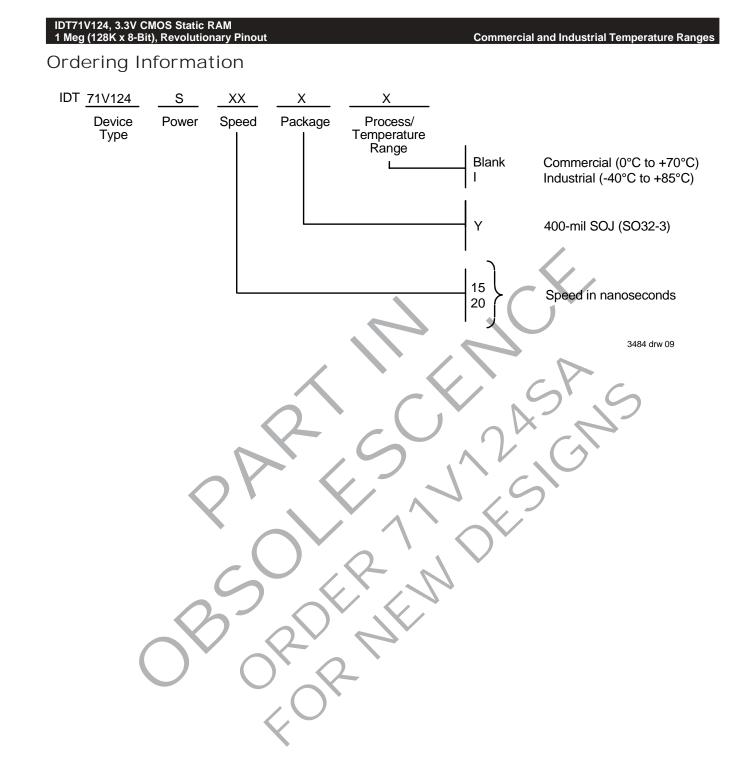
- 4. OE is LOW.
- 5. Transition is measured ±200mV from steady state.

Timing Waveform of Write Cycle No.1 (WE Controlled Timing)<sup>(1,2,4)</sup>



#### NOTES:

- 1. A write occurs during the overlap of a LOW  $\overline{CS}$  and a LOW  $\overline{WE}$ .
- OE is continuously HIGH. During a WE controlled write cycle with OE LOW, twp must be greater than or equal to twHZ + tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is HIGH during a WE controlled write cycle, this requirement does not apply and the minimum write pulse is the specified twp.
  During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the CS LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high impedance state. CS must be active during the tcw write period.
- 5. Transition is measured ±200mV from steady state.



## Datasheet Document History

- Updated to new format
- Pg. 2 Expressed commercial and industrial temperature ranges on DC Electrical table
- Pg. 2 Added Recommended Operating Temperature and Supply Voltage table
- Pg. 4 Expressed commercial and industrial ranges on AC Electrical table
- Pg. 4 Revised footnotes and notes on AC Electrical table
- Pg. 6 Revised footnotes on Write Cycle No. 1 diagram
- Pg. 8 Added datasheet document history

08/30/00
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Part in obsolescence; order part 71V124SA. See PDN# S-0004





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